

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.43749	100.0	6.3
			<b>Subtotal</b>	<b>0.43749</b>	<b>100</b>	<b>6.3</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01035	100.0	0.1491
	Pure metal	Aluminium (Al)	7429-90-5	0.1625	100.0	2.34
			<b>Subtotal</b>	<b>0.17285</b>	<b>200</b>	<b>2.4891</b>
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.73606	100.0	25
			<b>Subtotal</b>	<b>1.73606</b>	<b>100</b>	<b>25</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02333	0.04	0.336
	Copper alloy	Iron (Fe)	7439-89-6	0.05833	0.1	0.84
	Copper alloy	Copper (Cu)	7440-50-8	58.25008	99.86	838.824
			<b>Subtotal</b>	<b>58.33174</b>	<b>100</b>	<b>840</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.39835	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.24983	16.0	90
	Filler	Silica fused	60676-86-0	29.29608	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.11718	0.3	1.6875
			<b>Subtotal</b>	<b>39.06144</b>	<b>100</b>	<b>562.5</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.01302	5.0	0.1875
	Lead alloy	Silver (Ag)	7440-22-4	0.00651	2.5	0.09375
	Lead alloy	Lead (Pb)	7439-92-1	0.24088	92.5	3.46875
			<b>Subtotal</b>	<b>0.26041</b>	<b>100</b>	<b>3.75</b>
			<b>Total</b>	<b>99.99999</b>	<b>100</b>	<b>1440.0391</b>

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